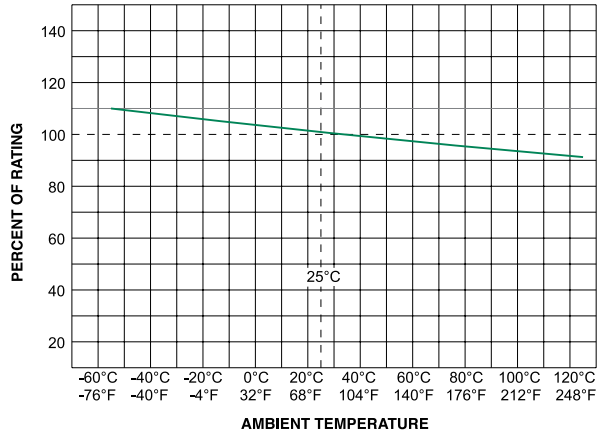


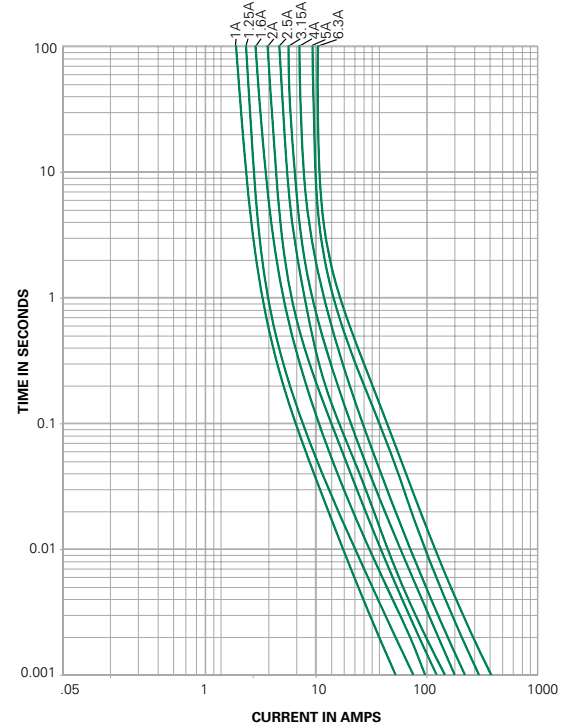
Temperature Re-rating Curve



Note:

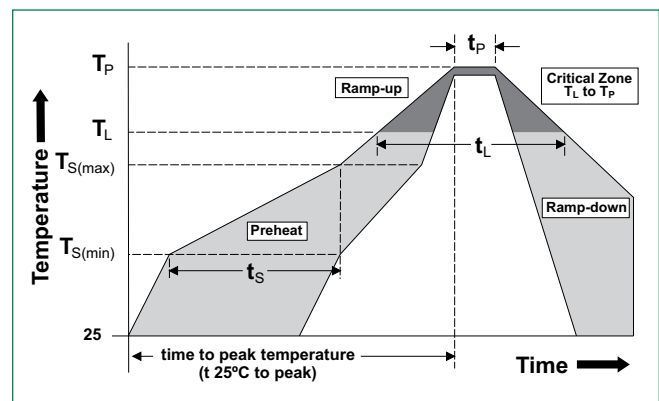
1. Rerating depicted in this curve is in addition to the standard derating of 15% for continuous operation.

Average Time Current Curves



Soldering Parameters

Reflow Condition		Pb – Free assembly
Pre Heat	- Temperature Min ($T_{s(min)}$)	150°C
	- Temperature Max ($T_{s(max)}$)	200°C
	- Time (Min to Max) (t_s)	60 - 180 secs
Average ramp up rate (Liquidus Temp (T_L) to peak		5°C/second max.
$T_{s(max)}$ to T_L - Ramp-up Rate		5°C/second max.
Reflow	- Temperature (T_L) (Liquidus)	217°C
	- Temperature (t_L)	60 - 150 secs
Peak Temperature (T_p)		260 ^{+0/-5} °C
Time within 5°C of actual peak Temperature (t_p)		20 – 40 seconds
Ramp-down Rate		5°C/second max.
Time 25°C to peak Temperature (T_p)		8 minutes max.
Do not exceed		260°C
Wave Soldering Parameters		260°C Peak Temperature, 3 seconds max.

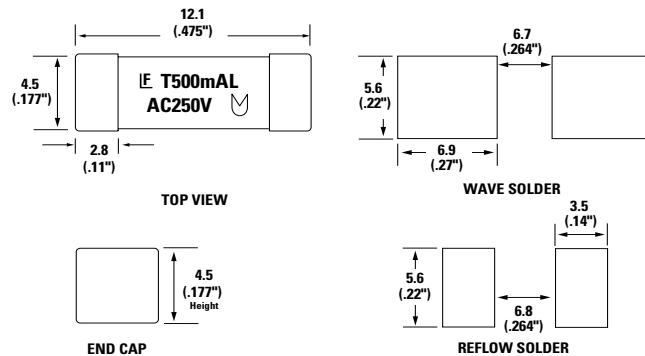


Product Characteristics

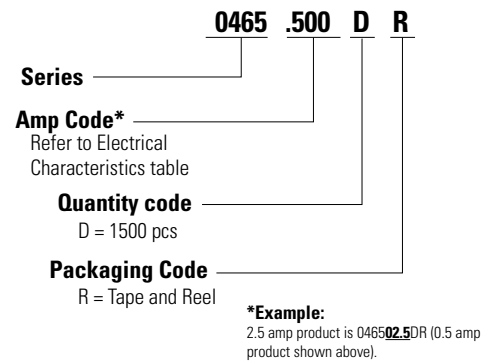
Materials	Body: High Performance Ceramic Terminations: Silver plated brass.
Product Marketing	Brand, Ampere Rating, Voltage Rating, UMF Logo
Operating Temperature	-55°C to 125°C
Moisture Sensitivity Level	J-STD-020, Level 1
Solderability	IEC 60127-4
Insulation Resistance (after opening)	IEC 60127-4 (0.1Mohm min @ 500VDC)
Shock	MIL-STD-202, Method 213, Test Condition A

Thermal Shock	MIL-STD-202, Method 107, Test Condition B, 5 cycles, -65°C to 125°C
Mechanical Shock	MIL-STD-202, Method 213, Test Condition A
Vibration	MIL-STD-202, Method 201 (10-55 Hz)
Moisture Resistance	MIL-STD-202, Method 106, 10 cycles
Salt Spray	MIL-STD-202, Method 101, Test Condition B (48hrs)
Resistance to Soldering Heat	IEC 60127-4

Dimensions



Part Numbering System



Packaging

Packaging Option	Packaging Specification	Quantity	Quantity & Packaging Code
24mm Tape and Reel	EIA RS-481-1 (IEC 60286-3)	1500	DR